

**S/N Unknown****PATENT****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Gurtej Singh Sandhu et al. Examiner: Unknown  
Serial No.: ~~Unknown~~ 09/652,619 Group Art Unit: Unknown  
Filed: ~~Herewith~~ 8/31/2000 Docket: 303.085US4  
Title: METHOD FOR FORMING A METALLIZATION LAYER

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for review in connection with the above-identified patent application. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner be returned to the Applicants.

In accordance with 37 C.F.R. §1.98(d), copies of the listed documents are not provided as these references were previously cited by or submitted to the U.S. Patent Office in connection with Applicants' prior U.S. application, Serial No. 08/912,051, filed on August 18, 1997, which is relied upon for an earlier filing date under 35 U.S.C. §120.

Applicants respectfully request consideration of these references during prosecution of the above-identified matter. The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

GURTEJ SINGH SANDHU ET AL.

By their Representatives,

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Date of Deposit: August 31, 2000

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.

8/31/2000

Sheet 1 of 1

Form 1449\*

Atty. Docket No.: 303.085US4

Serial No. ~~Unknown~~INFORMATION DISCLOSURE STATEMENT  
BY APPLICANT

Applicant: Gurtej Singh Sandhu et al.

(Use several sheets if necessary)

Filing Date: ~~Herewith~~ 8/31/2000Group: ~~Unknown~~ 2818

## U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
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**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes   No
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## OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

\*\*Examiner  
Initial

Examiner

Date Considered

\*Substitute Disclosure Statement Form (PTO-1449)

\*\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.